# Single Inverter with Open Drain Output

The MC74VHC1G05 is an advanced high speed CMOS inverter with open drain output fabricated with silicon gate CMOS technology.

The internal circuit is composed of three stages, including an open drain output which provides the capability to set output switching level. This allows the MC74VHC1G05 to be used to interface 5.0 V circuits to circuits of any voltage between  $V_{CC}$  and 7.0 V using an external resistor and power supply.

The MC74VHC1G05 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage.

- High Speed:  $t_{PD} = 3.8 \text{ ns}$  (Typ) at  $V_{CC} = 5.0 \text{ V}$
- Low Internal Power Dissipation:  $I_{CC} = 1 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FET = 105

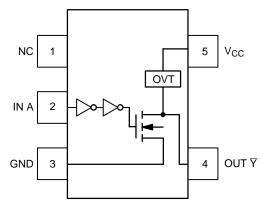


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A



**MARKING** 

Pin 1



SOT23-5/TSOP-5/SC59-5 DT SUFFIX CASE 483



d = Date Code

PIN ASSIGNMENT						
1	NC					
2	IN A					
3	GND					
4	OUT ₹					
5	V <sub>CC</sub>					

### **FUNCTION TABLE**

A Input	▼ Output
L	Z
Н	L

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

### **MAXIMUM RATINGS**

Symbol	Characte	eristics	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		-0.5 to 7.0	V
I <sub>IK</sub>	Input Diode Current		-20	mA
I <sub>OK</sub>	Output Diode Current	V <sub>OUT</sub> < GND; V <sub>OUT</sub> > V <sub>CC</sub>	+20	mA
l <sub>OUT</sub>	DC Output Current, per Pin		+25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND		+50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	· 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance	SC70-5/SC-88A/SOT-353 (Note 1) SOT23-5/TSOP-5/SC59-5	350 230	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A/SOT-353 SOT23-5/TSOP-5/SC59-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>LATCH-UP</sub>	Latch-Up Performance Above \	CC and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- Tested to EIA/JESD78.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Characteristics	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage		2.0	5.5	V
V <sub>IN</sub>	DC Input Voltage	0.0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage		0.0	7.0	V
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

## DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

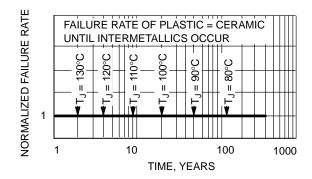


Figure 3. Failure Rate vs. Time Junction Temperature

### DC ELECTRICAL CHARACTERISTICS

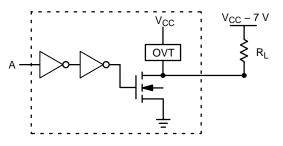
			V <sub>CC</sub>	•	Γ <sub>A</sub> = 25°	С	<b>T</b> <sub>A</sub> ≤	85°C	-55 ≤ T <sub>A</sub>	≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V <sub>OL</sub>	Maximum Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	$V_{IN} = V_{IH}$ $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		V <sub>IN</sub> = V <sub>IH</sub> I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
I <sub>LKG</sub>	Z-State Output Leakage Current	$V_{IN} = V_{IL}$ $V_{OUT} = V_{CC}$ or GND	5.5			±0.25		± 2.5		±5.0	μΑ
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μΑ
I <sub>OPD</sub>	Maximum Off-stat Leakage Current	V <sub>OUT</sub> = 5.5 V	0			0.25		2.5		5.0	μΑ

### AC ELECTRICAL CHARACTERISTICS Input $t_{\text{r}} = t_{\text{f}} = 3.0 \text{ ns}$

				Т	A = 25°	С	T <sub>A</sub> ≤ 85°C		-55 ≤ T <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Test Conditi	ions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PZL</sub>	Maximum Output Enable Time,	$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $R_L = R_I = 500 \Omega$	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		5.0 7.5	7.1 10.6		8.5 12.0		10.0 14.5	ns
	Input A to Y	$V_{CC} = 5.0 \pm 0.5 \text{ V}$ $R_L = R_I = 500 \Omega$	$C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		3.8 5.3	5.5 7.5		6.5 8.5		8.0 10.0	
t <sub>PLZ</sub>	Maximum Output Disable Time	$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $R_L = R_I = 500 \Omega$	C <sub>L</sub> = 50 pF		7.5	10.6		12.0		14.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V}$ $R_L = R_I = 500 \Omega$	C <sub>L</sub> = 50 pF		5.3	7.5		8.5		10.0	
C <sub>IN</sub>	Maximum Input Capacitance				4	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	18	pF

<sup>6.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC} \cdot C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .



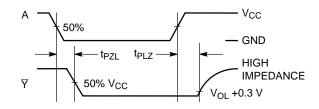
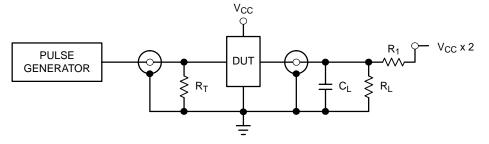


Figure 4. Output Voltage Mismatch Application

Figure 5. Switching Waveforms

Figure 8. LED Driver



 $C_L$  = 50 pF equivalent (Includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

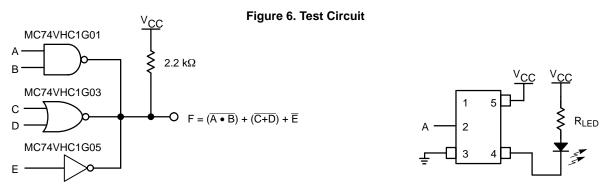


Figure 7. Complex Boolean Functions

MC74VHC1G05  $220 \Omega$ GTL

Figure 9. GTL Driver

### **DEVICE ORDERING INFORMATION**

	Device Nomenclature							
Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size <sup>†</sup>
MC74VHC1G05DFT1	МС	74	VHC1G	05	DF	T1	SC70-5/SC-88A/S OT-353	178 mm (7 in) 3000 Unit
MC74VHC1G05DFT2	МС	74	VHC1G	05	DF	T2	SC70-5/SC-88A/S OT-353	178 mm (7 in) 3000 Unit
MC74VHC1G05DTT1	MC	74	VHC1G	05	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

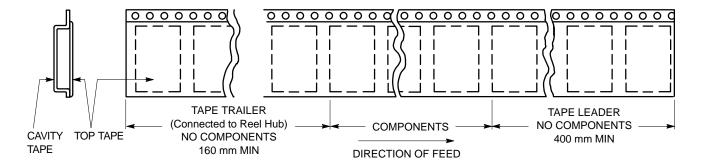


Figure 10. Tape Ends for Finished Goods

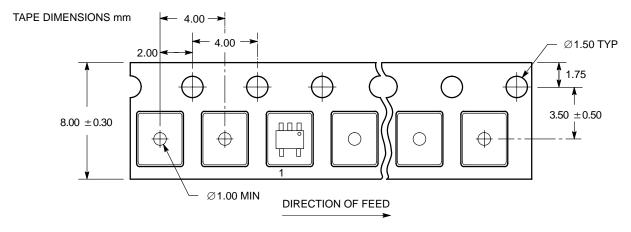


Figure 11. SC-70-5/SC-88A/SOT-353 DFT1 Reel Configuration/Orientation

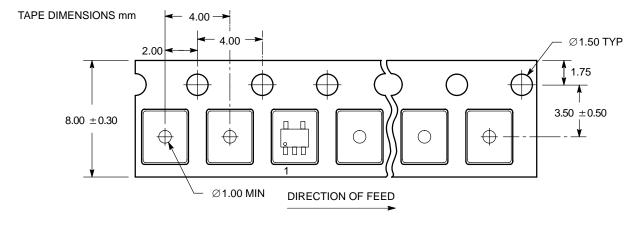


Figure 12. SC-70/SC-88A/SOT-353 DFT2 and SOT23-5/TSOP-5/SC59-5 DTT1 Reel Configuration/Orientation

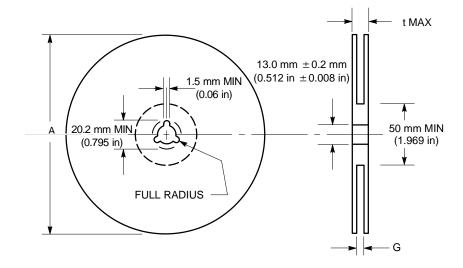


Figure 13. Reel Dimensions

### **REEL DIMENSIONS**

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

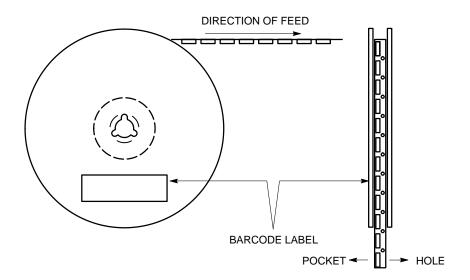
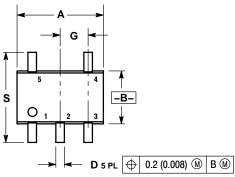


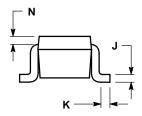
Figure 14. Reel Winding Direction

### **PACKAGE DIMENSIONS**

### SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 **ISSUE G** 





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419A-01 OBSOLETE. NEW STANDARD
- 419A-02.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008	0.008 REF		REF	
S	0.079	0.087	2 00	2 20	

### **SOLDERING FOOTPRINT\***

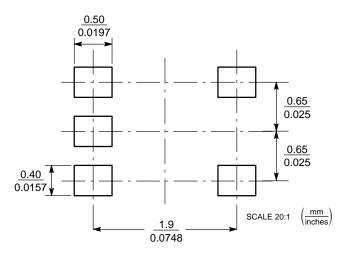


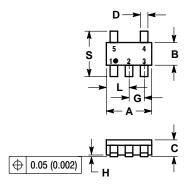
Figure 15. SC-88A/SC70-5/SOT-353

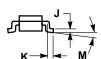
<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS

### SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-01 ISSUE C





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI 114-3M, 1992.
  CONTROLLING DIMENSION: MILLIMETER.
  MAXIMUM LEAD THICKNESS INCLUDES
  LEAD FINISH THICKNESS. MINIMUM LEAD
  THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.1142	0.1220	
В	1.30	1.70	0.0512	0.0669	
С	0.90	1.10	0.0354	0.0433	
D	0.25	0.50	0.0098	0.0197	
G	0.85	1.05	0.0335	0.0413	
Н	0.013	0.100	0.0005	0.0040	
۲	0.10	0.26	0.0040	0.0102	
K	0.20	0.60	0.0079	0.0236	
L	1.25	1.55	0.0493	0.0610	
М	0	10	0	10	
S	2.50	3.00	$0.098\overline{5}$	0.1181	

### **SOLDERING FOOTPRINT\***

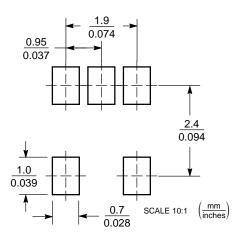


Figure 16. THIN SOT23-5/TSOP-5/SC59-5

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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